

Title (en)
METHOD FOR PRODUCING THREE-DIMENSIONAL, SELECTIVELY METALLIZED PARTS AND A THREE-DIMENSIONAL, SELECTIVELY METALLIZED PART

Title (de)
VERFAHREN ZUR HERSTELLUNG VON DREIDIMENSIONALEN SELEKTIV METALLISIERTEN TEILEN UND DREIDIMENSIONALES SELEKTIV METALLISIERTES TEIL

Title (fr)
PROCEDE DE FABRICATION DE PIECES TRIDIMENSIONNELLES METALLISEES DE MANIERE SELECTIVE ET PIECE TRIDIMENSIONNELLE METALLISEE DE MANIERE SELECTIVE

Publication
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Application
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Priority
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Abstract (en)
[origin: US2001045361A1] The parts are produced by two-component injection molding. Those regions that are to be metallized consist of a first plastic and those regions that are not to be metallized consist of a second plastic. After the entire surface of the parts has been seeded, the seeding is selectively removed with the aid of a solvent in the regions which are not to be metallized. The first plastic is insoluble and the second plastic soluble in the solvent. The selective metallization then takes place by electroless metal deposition and, if appropriate, electrodeposition of metal.

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